



Sierra Components, Inc.

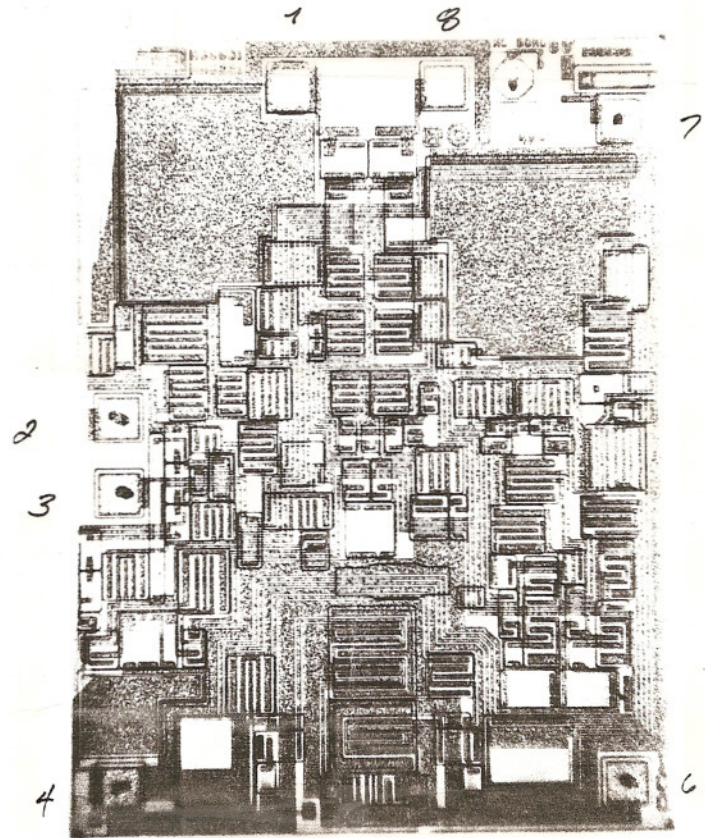
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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

PAD FUNCTIONS

- 1) -BAL
- 2) -IN
- 3) +IN
- 4) -V
- 5) NC
- 6) VOUT
- 7) +V
- 8) +BAL



Topside Metal: Al
Backside: Si
Backside Potential: V-
Mask Ref: 50246A
Bond Pads: .004" min

APPROVED BY: CB
MFG: HARRIS

DIE SIZE: .103" x .072"
THICKNESS: .019"

DATE: 1/26/01
P/N: HAO-5221-6